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(54) Title: METHOD FOR SELECTIVELY COVERING A MICRO MACHINED SURFACE

(57) Abstract: On a die that has etchings on a surface, firstly a sheet of negative photoresist is laid down which, by means of an exposure and subsequent development, is left only above the etchings; then, upon the negative photoresist, a positive photoresist is applied, which is subjected to exposure and development to produce functional geometries deposited in thin film; subsequently the positive photoresist is removed in a "lift-off" operation, and the negative photoresist is taken off in a plasma operation, thus revealing the etchings.



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